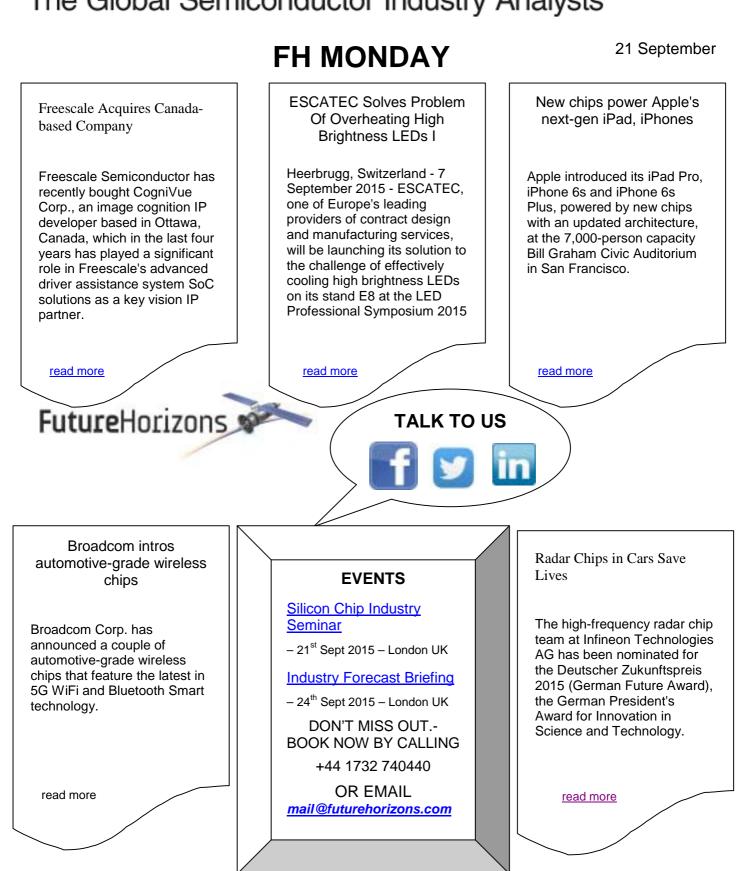
FutureHorizons



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Freescale Acquires Canada-based Image Cognition IP company

Freescale Semiconductor has recently bought CogniVue Corp., an image cognition IP developer based in Ottawa, Canada, which in the last four years has played a significant role in Freescale's advanced driver assistance system SoC solutions as a key vision IP partner.

By bringing CogniVue's IP and its development team in-house, Freescale hopes to lead the safety-critical ADAS and eventually autonomous car market with its own IP, developed from the very start as "automotive qualified."

Davide Santo, Freescale's safety and chassis segment manager based in Munich, explained that safety can't be an afterthought. He stated that the acquisition of CogniVue affords Freescale the opportunity to develop vision IP "that's designed in lockstep with Freescale's automotive safety requirement knowledge." This will "ease our internal work," and "our integration of safety-critical hardware and software," he added.

ESCATEC Solves Problem Of Overheating High Brightness LEDs

Heerbrugg, Switzerland - 7 September 2015 - ESCATEC, one of Europe's leading providers of contract design and manufacturing services, will be launching its solution to the challenge of effectively cooling high brightness LEDs on its stand E8 at the LED Professional Symposium 2015 in Bregenz, Austria on 22-24 September 2015. http://www.led-professional-symposium.com

ESCATEC's Heat Spreader solution solders the LEDs onto a copper substrate, which is up to ten times more effective at dissipating the heat generated by the LEDs than current solutions. The CoolRunning design means that LEDs with a power density of up to 10W per mm2 could be passively cooled.

The Heat Spreader was developed in response to a customer visit to ESCATEC's FutureLab where novel and innovative solutions are developed for LED applications. "Heat dissipation is always a challenge for LEDs as their compact size means that the LEDs can be packed close together to form a powerful illumination source but that also forms a highly concentrated heat source, for example, when a hundred 5 Amp LEDs are side by side," explained Wolfgang Plank, Manager of the FutureLab. "Our novel Heat Spreader solution opens up compact, high power LEDs of, say 1000W, to be used in many new applications such as stage lighting, architectural illumination and video projectors."

New chips power Apple's next-gen iPad, iPhones

Apple introduced its iPad Pro, iPhone 6s and iPhone 6s Plus, powered by new chips with an updated architecture, at the 7,000-person capacity Bill Graham Civic Auditorium in San Francisco.

The iPad Pro runs on a 64bit A9X, Apple's third generation of custom designed processors. While Apple was expectedly short on details, officials announced that A9X has twice the memory bandwidth of last year's A8X and is 1.8 times faster than the 8X processor inside the MacBook Air 2 for "desktop-class performance." The tablet supports 802.11ac MIMO and up to 150Mbit/s LTE.

The iPad Pro is faster than 80 per cent of the PCs that shipped in the past six months, said Apple Vice President of Worldwide Marketing Phil Schiller, and its graphics are faster than 90 per cent of those PCs. This is due in large part to an updated transistor architecture—likely a 14nm or 16nm FinFET process from Samsung or TSMC.

Broadcom intros automotive-grade wireless chips

Broadcom Corp. has announced a couple of automotive-grade wireless chips that feature the latest in 5G WiFi and Bluetooth Smart technology. The devices allow car makers and tier one integrators to deliver high-speed connectivity within and beyond the vehicle, providing Internet, cloud applications and entertainment content via telematics or hot spot connections, stated the company.

Broadcom offers the 5G WiFi/Bluetooth Smart 2X2 MIMO combo chip with Real Simultaneous Dual Band (RSDB) support as well as a stand-alone tri-mode Bluetooth Smart (version 4.2) SoC. Optimised to meet the rigorous standards of the automotive industry, all products have been tested to AECQ100 automotive environmental stress requirements, are manufactured in TS16949 certified facilities and offer full production part approval process (PPAP) support.

Radar Chips in Cars Save Lives:

Munich, Germany – September 16, 2015 – The high-frequency radar chip team at Infineon Technologies AG has been nominated for the Deutscher Zukunftspreis 2015 (German Future Award), the German President's Award for Innovation in Science and Technology. Radar systems in cars make a major contribution to improving road safety. They measure the distance to other vehicles and their speed in relation to each other in order to give drivers early warning and trigger braking in emergencies.

"Radar is a very sophisticated technology. It helps to prevent road accidents and save lives, and also makes driving much more comfortable, for instance in lines of traffic. With innovative solutions, the Infineon team has managed to reduce the cost of radar systems considerably. Radar systems that have been confined to drivers of premium cars to date will become affordable for all drivers," says Dr. Reinhard Ploss, CEO of Infineon Technologies AG. "The nomination acknowledges our employees' outstanding achievements. It is an incentive for further innovations that will not only bring about technical novelties but also prevail on the market and improve people's lives."